

KYOCERA KE-G1250 LKDS

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

Special Epoxy Molding Compounds Optimizing Warpage and Applicable to Fine Pitch Wire for BGA Package

Strong Points

Less Warpage in All Types of Area Array Packages due to High Tg Characteristic.

Applicable to Fine Pitch Wire Bonding with Good Wire Sweep Performance.

Achieve High Yield after Molding due to Excellent Moldability that allows its application to MAP.

Application

Standard P-BGA, HS-BGA and LGA Package.

Multi Chip Module (Stacked or Side by Side Layout)

IC Card, Memory Card etc.

Low Alpha Ray Type: KE-G2250 LKDS

| General Information | | |
|------------------------------|------------------------------------|-------------------|
| Features | Good Moldability | |
| Uses | Electrical/Electronic Applications | |
| Physical | Nominal Value | Unit |
| Specific Gravity | 2.00 | g/cm ³ |
| Spiral Flow | 180 | cm |
| Solution Viscosity | 7000 | mPa·s |
| Mechanical | Nominal Value | Unit |
| Flexural Modulus | 25000 | MPa |
| Flexural Strength | 180 | MPa |
| Thermal | Nominal Value | Unit |
| Glass Transition Temperature | 130 | °C |
| CLTE - Flow | | |
| -- ¹ | 8.0E-6 | cm/cm/°C |
| -- ² | 3.2E-5 | cm/cm/°C |
| NOTE | | |
| 1. | Alpha 1 | |
| 2. | Alpha 2 | |

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